

IFW/AF



Docket No.: M1071.1711  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Hidekiyo Takaoka et al.

Application No.: 10/087,742

Confirmation No.: 7012

Filed: March 5, 2002

Art Unit: 1742

For: LEAD FREE SOLDER AND SOLDERED  
ARTICLE

Examiner: S. Ip

STATUS INQUIRY

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

It is respectfully requested that the attorney named below be advised of the status of the above-identified application. Please advise us of when we might expect to receive from the Patent and Trademark Office a response to the Appeal Brief we filed on October 29, 2004.

Dated: March 1, 2005

Respectfully submitted

By Richard LaCava

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